



# SOT938-1

plastic, heatsink small outline package; 36 leads; low stand-off height

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HSOP36
<b>Package type industry code</b>	HSOP36
<b>Package style descriptive code</b>	HSOP (heatsink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	7-4-2006

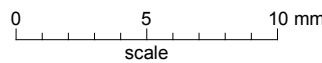
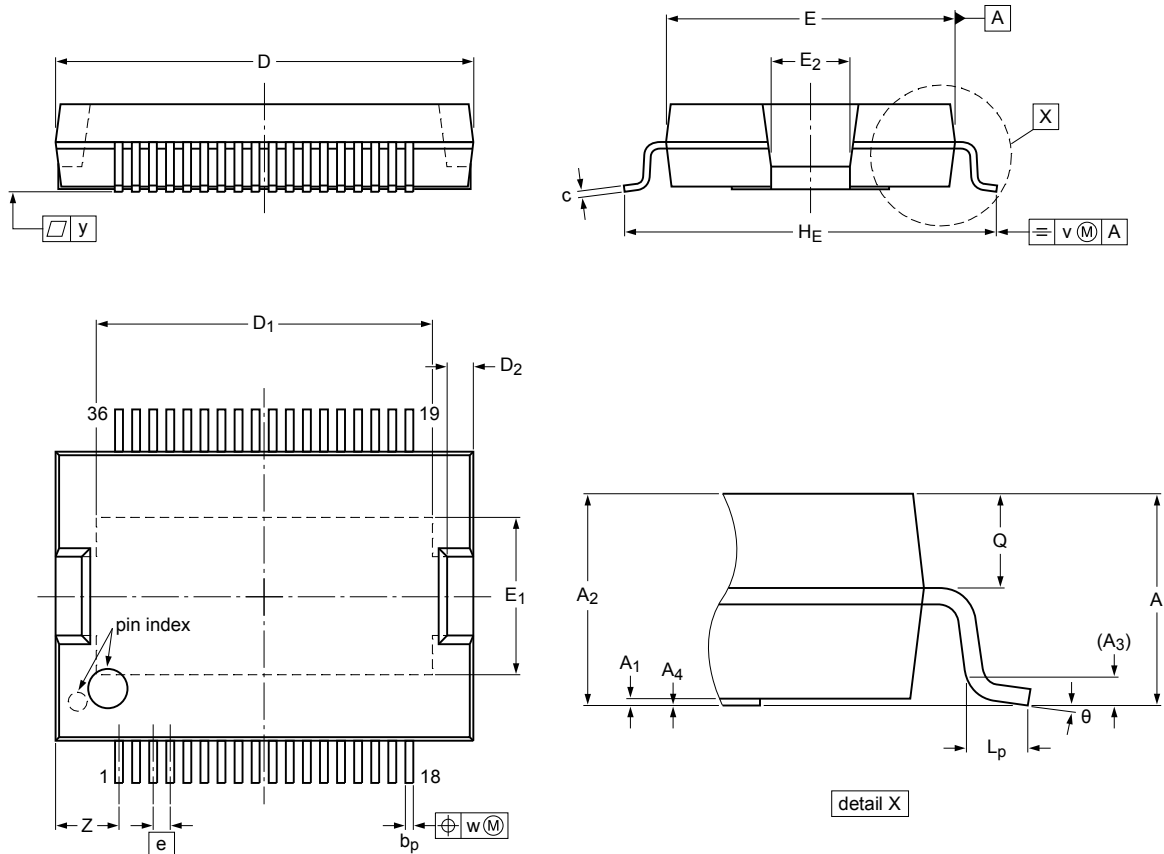
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.8	-	15.9	16	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	[tbd]	-	3.6	3.6	mm
A <sub>2</sub>	package height	3.2	-	3.35	3.5	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	36	-	



2. Package outline

HSOP36: plastic, heatsink small outline package; 36 leads; low stand-off height SOT938-1



Dimensions

Unit <sup>(1)</sup>	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	A <sub>4</sub> <sup>(1)</sup>	b <sub>p</sub>	c	D <sup>(2)</sup>	D <sub>1</sub>	D <sub>2</sub>	E <sup>(2)</sup>	E <sub>1</sub>	E <sub>2</sub>	e	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y	z	
max		0.3	3.5		0.1	0.38	0.32	16.0	13.0	1.1	11.1	6.2	2.9		14.5	1.1	1.5					2.55
mm nom	3.6			0.35										0.65				0.25	0.12	0.1		
min		0.1	3.2		0.0	0.25	0.23	15.8	12.6	0.9	10.9	5.8	2.5		13.9	0.8	1.4					2.20

Note

- Limits per individual lead.
- Plastic or metal protrusions of 0.25 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT938-1					-06-04-07- 10-10-21

Fig. 1. Package outline HSOP36 (SOT938-1)

### 3. Legal information

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